This listing of claims will replace all prior versions of claims in the application.

- Claim 1. (currently amended) A coated substrate comprising:
 an antireflective composition layer comprising as separate components (i) a basic
 material, (ii) a crosslinker, (iii) an acid or acid generator compound, and (iv) a resin, and
 a photoresist layer over the antireflective composition layer, the photoresist comprising a
 resin that comprises photoacid-labile acetal or ketal groups.
- Claim 2. (original) The substrate of claim 1 wherein the basic material has a pKa of about 3 or greater.
- Claim 3. (original) The substrate of claim 1 wherein the basic material has a pKa of about 6 or greater.
- Claim 4. (original) The substrate of claim 1 wherein the basic material has a pKa of about 9 or greater.
- Claim 5. (previously presented) The substrate of claim 1 wherein the basic material contains one or more N, O or S atoms.
- Claim 6. (previously presented) The substrate of claim 1 wherein the basic material contains one or more amine groups.
- Claim 7. (previously presented) The substrate of claim 1 wherein the basic material contains one or more hydroxy, ether, or sulfide groups.
- Claim 8. (previously presented) The substrate of claim 1 wherein the basic material has a molecular weight of less than about 500.

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- Claim 9. (previously presented) The substrate of claim 1 wherein the basic material is a polymeric material
- Claim 10. (previously presented) The substrate of claim 1 wherein the antireflective composition is crosslinked.
- Claim 11. (previously presented) The substrate of claim 1 wherein the antireflective composition comprises an acid or acid generator compound.
- Claim 12. (previously presented) The substrate of claim 1 wherein the antireflective composition comprises a thermal acid generator and a photoacid generator compound.
- Claim 13. (previously presented) The substrate of claim 1 wherein the antireflective layer comprises a resin distinct from a polymeric basic material.
- Claim 14. (previously presented) The substrate of claim 1 wherein the antireflective layer comprises aromatic groups.
- Claim 15. (previously presented) The substrate of claim 1 wherein the antireflective layer comprises anthracenyl, naphthylene or phenyl groups.

Claims 16-17. (cancelled)

- Claim 18. (currently amended) A method for forming a photoresist relief image, comprising:
- applying an antireflective composition on a substrate, the antireflective composition comprising as separate components (i) a basic material, (ii) a crosslinker, (iii) an acid or acid generator compound, and (iv) a resin,

applying a photoresist layer over the antireflective composition layer, the photoresist comprising a resin that comprises photoacid-labile acetal or ketal groups; and exposing and developing the photoresist layer to provide a resist relief image.

- Claim 19. (original) The method of claim 18 wherein the antireflective layer is crosslinked prior to application of the photoresist layer.
- Claim 20. (original) The method of claim 18 wherein the antireflective layer is thermally cured prior to application of the photoresist layer.
- Claim 21. (previously presented) The method of claim 18 wherein the basic material has a pKa of about 3 or greater.
- Claim 22. (previously presented) The method of claim 18 wherein the basic material has a pKa of about 6 or greater.
- Claim 23. (previously presented) The method of claim 18 wherein the basic material has a pKa of about 9 or greater.
- Claim 24. (previously presented) The method of claim 18 wherein the basic material contains one or more N, O or S atoms.

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- Claim 25. (previously presented) The method of claim 18 wherein the basic material contains one or more amine groups.
- Claim 26. (previously presented) The method of claim 18 wherein the basic material contains one or more hydroxy, ether, or sulfide groups.
- Claim 27. (previously presented) The method of claim 18 wherein the basic material has a molecular weight of less than about 500.
- Claim 28. (previously presented) The method of claim 18 wherein the basic material is a polymeric material
- Claim 29. (previously presented) The method of claim 18 wherein the antireflective composition comprises an acid or acid generator compound.
- Claim 30. (previously presented) The method of claim 18 wherein the antireflective composition comprises a thermal acid generator and a photoacid generator compound.
- Claim 31. (previously presented) The method of claim 18 wherein the antireflective layer comprises a resin distinct from a polymeric basic material.
- Claim 32. (previously presented) The method of claim 18 wherein the antireflective layer comprises aromatic groups.
- Claim 33. (previously presented) The method of claim 18 wherein the photoresist layer is exposed with patterned radiation having a wavelength of about 260 nm or less.

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- Claim 34. (previously presented) The method of claim 18 wherein the photoresist layer is exposed with patterned radiation having a wavelength of about 248 nm, 193 nm or 157 nm.
- Claim 35. (previously presented) The method of claim 18 wherein the photoresist layer is exposed with radiation having a wavelength of about 248 nm and the antireflective layer comprises anthracenyl or naphthylene groups.
- Claim 36. (previously presented) The method of claim 18 wherein the photoresist layer is exposed with radiation having a wavelength of about 193 nm and the antireflective layer comprises phenyl group.

Claims 37-48. (cancelled)

- Claim 49. (new) The method of claim 18 wherein the photoresist layer is exposed with patterned radiation having a wavelength of about 193 nm.
- Claim 50. (new) The substrate of claim 1 wherein the antireflective composition comprises the antireflective composition a thermal acid generator compound.
- Claim 51. (new) The method of claim 18 wherein the antireflective composition comprises a thermal acid generator compound.